

Please replace claims 8 and 13 as shown below. A marked up version of the amended claims is attached to this Amendment.

8. (Amended) A micromechanical device comprising:
 - a substrate;
 - a first micromechanical structure supported on the substrate and having a first vertical sidewall;
 - a second micromechanical structure supported on the substrate and having a second vertical sidewall; and
 - a first submicron, sacrificial-film-determined lateral gap between the first and second vertical sidewalls to increase electromechanical coupling of the first and second micromechanical structures.
13. (Amended) The device as claimed in claim 8 wherein the first micromechanical structure has a third vertical sidewall and wherein the device further comprises a third micromechanical structure supported on the substrate and having a fourth vertical sidewall and a second submicron, sacrificial-film-determined lateral gap between the third and fourth vertical sidewalls to increase electromechanical coupling of the first and third micromechanical structures.

Add new Claims 27-34 as follows:

27. (New) A micromechanical device comprising:
 - a substrate;
 - a first micromechanical structure supported on the substrate and having a first vertical sidewall;
 - a second micromechanical structure supported on the substrate and having a second vertical sidewall; and
 - a first submicron lateral gap between the first and second vertical sidewalls to increase electromechanical coupling of the first and second micromechanical structures;

wherein the second micromechanical structure comprises a material selected from the group consisting of plated metal and epitaxial polysilicon.

28. (New) A micromechanical device comprising:
 - a substrate;
 - a first micromechanical structure supported on the substrate and having a first vertical sidewall;
 - a second micromechanical structure supported on the substrate and having a second vertical sidewall; and
 - a first submicron lateral gap between the first and second vertical sidewalls to increase electromechanical coupling of the first and second micromechanical structures;
 - wherein a material characteristic of the first and second micromechanical structures is different.

29. (New) The device as claimed in claim 28 wherein the characteristic is grain size.

30. (New) The device as claimed in claim 28 wherein the first and second structures are made of the same material.

31. (New) The device as claimed in claim 30 wherein the same material is poly.

32. (New) The device as claimed in claim 31 wherein one poly is LPCVD poly and the other poly is epi-poly-Si.

33. (New) The device as claimed in claim 28 wherein the first and second structures are made of different materials.

34. (New) The device as claimed in claim 33 wherein the different materials are plated metal and poly-Si.